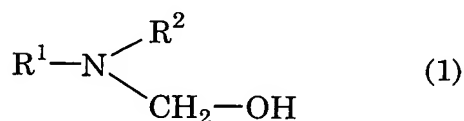


WHAT IS CLAIMED IS:

1. A cleaning composition comprising a N-hydroxyformamide.
2. The cleaning composition according to Claim 1, wherein the content of the N-hydroxyformamide is 0.001 to 95% by weight.
- 5 3. The cleaning composition according to Claim 1, further comprising an alkaline compound.
4. The cleaning composition according to Claim 3, wherein the alkaline compound is free from metallic element.
5. The cleaning composition according to Claim 3, wherein the alkaline
10 compound is at least one compound selected from the group consisting of alkyl amines, alkanol amines, polyamines, hydroxyl amine compounds, cyclic amines, and quaternary ammonium salts.
6. The cleaning composition according to Claim 1, further comprising an organic solvent.
- 15 7. The cleaning composition according to Claim 1, further comprising a corrosion inhibitor.
8. The cleaning composition according to Claim 1, further comprising an amine polymer having an average molecular weight of 250 or more.
9. The cleaning composition according to Claim 8, wherein the amine
20 polymer is at least one polymer selected from the group consisting of polyallylamines, polyethyleneimines and polyvinylamines.
10. The cleaning composition according to Claim 1, further comprising a compound having a hydroxymethylamino structure represented by the following formula (1):



wherein R^1 and R^2 are each independently hydrogen or substituent having 1 to 12 carbon atoms, R^1 and R^2 optionally being bonded to each other to form

together with nitrogen a ring structure having 2 to 12 carbon atoms.

11. The cleaning composition according to Claim 1, further comprising water.

12. A method for cleaning a substrate of semiconductor integrated circuits
5 or liquid crystal display devices, the method comprising a step of bringing the substrate into contact with the cleaning composition as defined in Claim 1.